

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10043709	01/09/2002	25	878	2811	F-A-2 60

**APPLICANTS: Chou Kuo-Yu; Lee Tze-Liang; Ong Tong-Chern;

**CONTINUING DATA VERIFIED: *No*

** FOREIGN APPLICATIONS VERIFIED: *No*

PG-PUB <input type="checkbox"/>	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed: 35 USC 119 conditions met		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input checked="" type="checkbox"/> no
Verified and Acknowledged Examiner's initials <i>TL</i>		ATTORNEY DOCKET NO 67,200-603

TITLE : Single layer wiring bond pad with optimum AL film thickness in Cu/FSG process for devices under 100s

U.S. DEPT. OF COMM /PAT & TM-PTO-435L(Rev. 12-84)

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due

Date Paid

TERMINAL

DISCLAIMER

Assistant Examiner

Primary Examiner

PREPARED FOR ISSUE

CLAIMS ALLOWED

Total Claims

Print Claim for
O.G.

DRAWING

Sheet(s) Drawn

Fig(s) Drawn

Print Fig.

Application Examiner

WARNING: The information disclosed herein may be restricted.
Unauthorized disclosure may be prohibited by the United States Code Title 35
Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark
Office is restricted to authorized employees and contractors only.

FILED WITH:

DISK (CRF)

CD-ROM
(Attached in pocket on right inside flap)